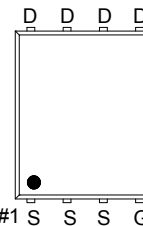
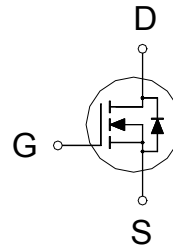


PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D^4
30V	1.6mΩ	151A



G. GATE
D. DRAIN
S. SOURCE

100% UIS Tested
100% Rg Tested

Features

- Pb-Free, Halogen Free and RoHS compliant.
- Low $R_{DS(on)}$ to Minimize Conduction Losses.
- Ohmic Region Good $R_{DS(on)}$ Ratio.
- Optimized Gate Charge to Minimize Switching Losses.

Applications

- Protection Circuits Applications.
- Computer for DC to DC Converters Applications.

ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ °C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current ⁴	$T_C = 25\text{ °C}$	I_D	151	A
	$T_C = 100\text{ °C}$		95	
Pulsed Drain Current ¹		I_{DM}	200	
Continuous Drain Current	$T_A = 25\text{ °C}$	I_D	36	
	$T_A = 70\text{ °C}$		28	
Avalanche Current		I_{AS}	57	
Avalanche Energy	$L = 0.1\text{mH}$	E_{AS}	162	mJ
Power Dissipation	$T_C = 25\text{ °C}$	P_D	73	W
	$T_C = 100\text{ °C}$		29	
Power Dissipation ³	$T_A = 25\text{ °C}$	P_D	4.1	W
	$T_A = 70\text{ °C}$		2.6	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient ²	$t \leq 10s$	$R_{\theta JA}$		30	°C / W
Junction-to-Ambient ²	Steady-State	$R_{\theta JA}$		50	
Junction-to-Case	Steady-State	$R_{\theta JC}$		1.7	

¹Pulse width limited by maximum junction temperature.

²The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ C$.

³The Power dissipation is based on $R_{\theta JA} t \leq 10s$ value.

⁴The maximum current rating is package limited.

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT	
			MIN	TYP	MAX		
STATIC							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1.3	1.6	2.35	V	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 20V$			±100	nA	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24V, V_{GS} = 0V$			1	μA	
		$V_{DS} = 20V, V_{GS} = 0V, T_J = 55^\circ C$			10		
Drain-Source On-State Resistance ¹	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 20A$		1.6	2.3	mΩ	
		$V_{GS} = 10V, I_D = 20A$		1.1	1.6		
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 20A$		123		S	
DYNAMIC							
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		3499		pF	
Output Capacitance	C_{oss}			625			
Reverse Transfer Capacitance	C_{rss}			408			
Gate Resistance	R_g	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$		1.1		Ω	
Total Gate Charge ²	Q_g	$V_{GS} = 10V$	$V_{DS} = 15V, V_{GS} = 10V, I_D = 20A$		70	nC	
		$V_{GS} = 4.5V$			36		
Gate-Source Charge ²	Q_{gs}			9.2			
Gate-Drain Charge ²	Q_{gd}			17			
Turn-On Delay Time ²	$t_{d(on)}$	$V_{DS} = 15V, I_D \cong 20A, V_{GS} = 10V, R_{GEN} = 6\Omega$			20		nS
Rise Time ²	t_r				120		
Turn-Off Delay Time ²	$t_{d(off)}$				97		
Fall Time ²	t_f			150			

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_J = 25 °C)

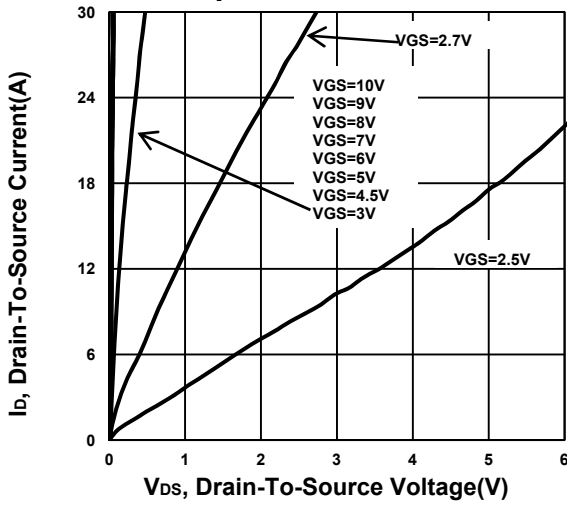
Continuous Current ³	I _S			73	A
Forward Voltage ¹	V _{SD}	I _F = 20A, V _{GS} = 0V		1	V
Reverse Recovery Time	t _{rr}	I _F = 20A, di _F /dt = 100A / μS		28	nS
Reverse Recovery Charge	Q _{rr}			13	nC

¹Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

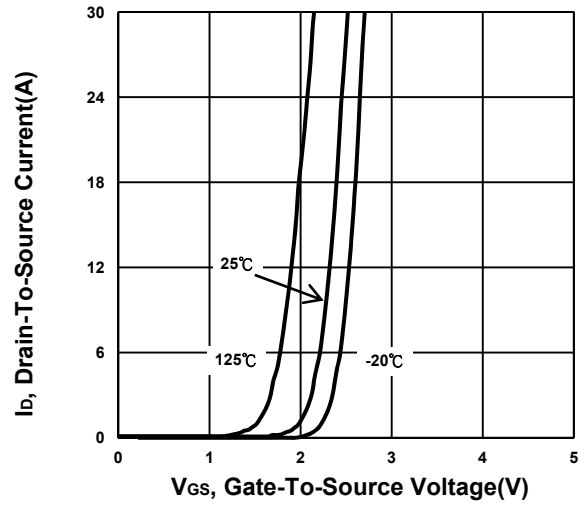
²Independent of operating temperature.

³The maximum current rating is package limited.

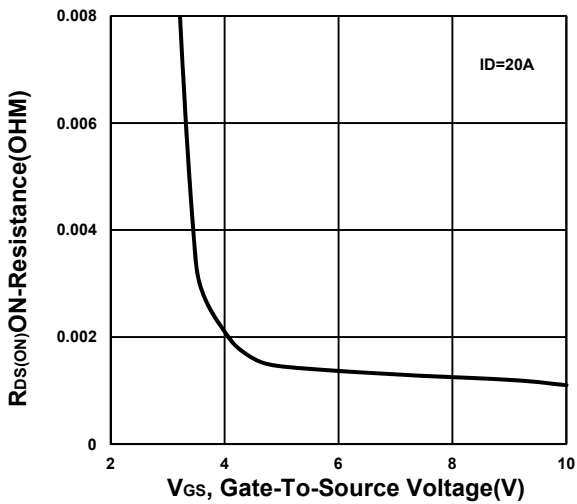
Output Characteristics



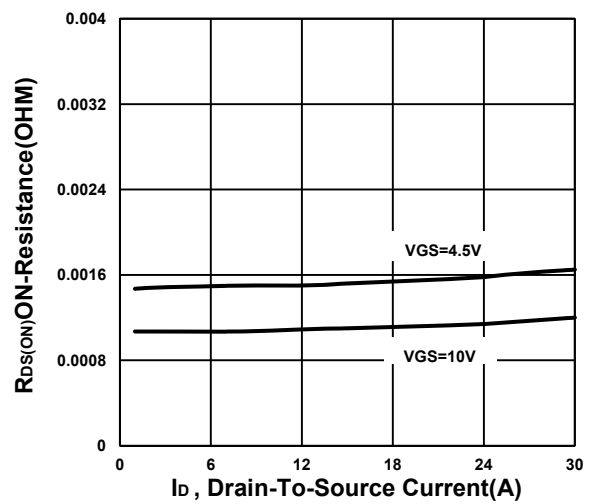
Transfer Characteristics



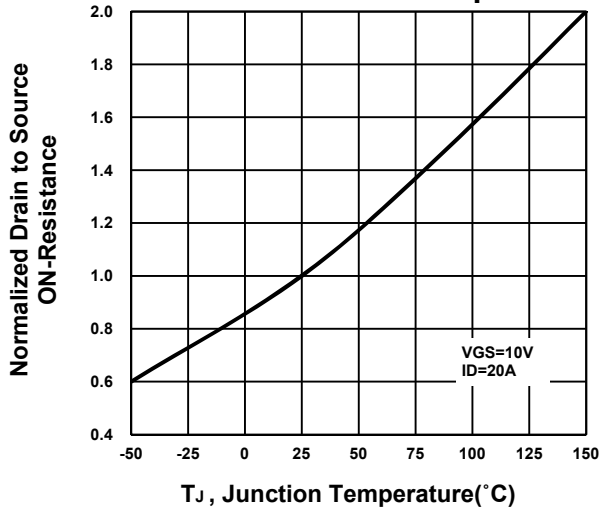
On-Resistance VS Gate-To-Source



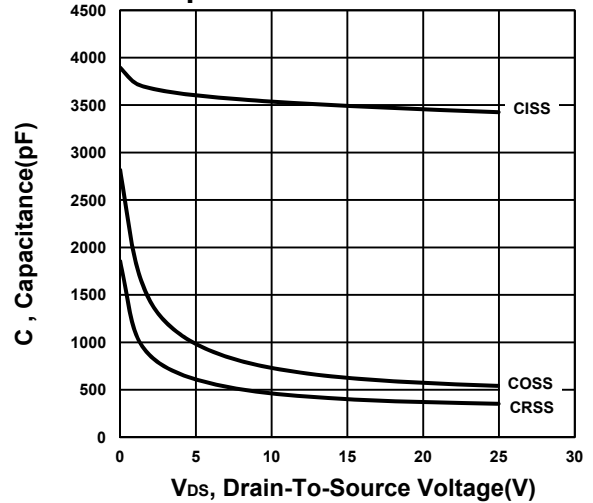
On-Resistance VS Drain Current



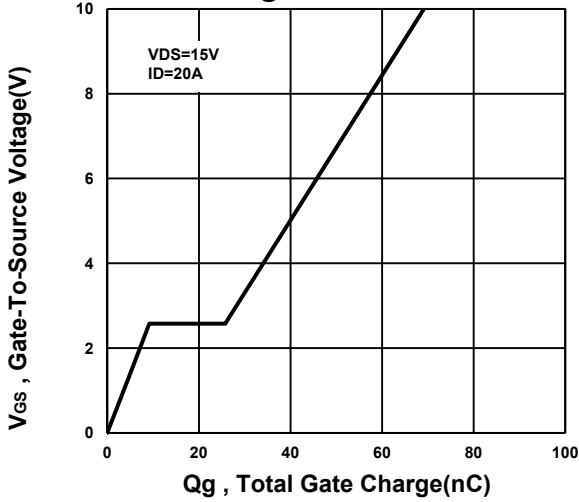
On-Resistance VS Temperature



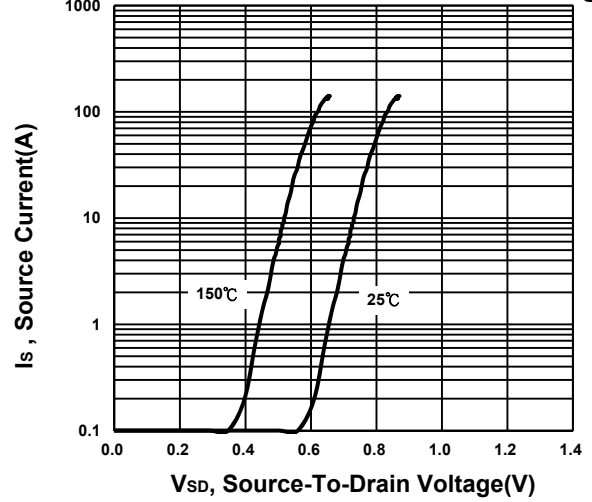
Capacitance Characteristic



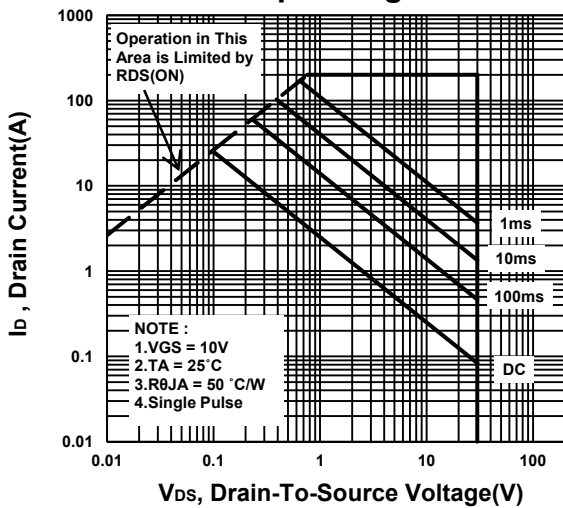
Gate charge Characteristics



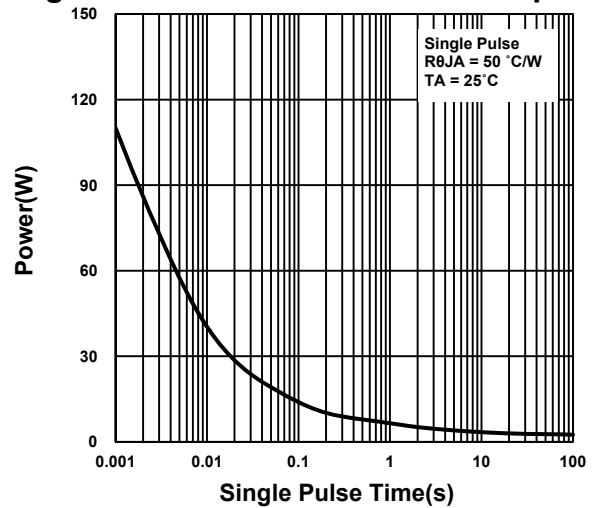
Source-Drain Diode Forward Voltage



Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve

